

Title (en)

COPPER ALLOY MATERIAL FOR ELECTRICAL/ELECTRONIC PART AND PROCESS FOR PRODUCING THE SAME

Title (de)

KUPFERLEGIERUNGSWERKSTOFF FÜR ELEKTRISCHES/ELEKTRONISCHES TEIL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

ALLIAGE DE CUIVRE POUR PIÈCES ÉLECTRIQUES/ÉLECTRONIQUES, ET PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication

EP 2088215 A4 20120627 (EN)

Application

EP 07829424 A 20071009

Priority

- JP 2007069686 W 20071009
- JP 2006276808 A 20061010
- JP 2007260386 A 20071003

Abstract (en)

[origin: US2009229716A1] A copper alloy material for electric/electronic parts, which is produced by the steps containing: finish rolling a copper alloy at a reduction ratio of 40% or less, subjecting the copper alloy finish-rolled to a heat treatment under the conditions at a temperature from 500° C. to 800° C. for a time period from 1 second to 100 seconds by means of a continuous annealing line, and strain relief annealing the copper alloy heat-treated under the conditions at a temperature from 400° C. to 600° C. for a time period from 30 seconds to 1000 seconds, wherein the copper alloy material for electric/electronic parts has rates of dimensional changes before and after the strain relief annealing in both directions parallel to and perpendicular to the rolling direction within the range from -0.02% to +0.02%.

IPC 8 full level

C22C 9/06 (2006.01); **B21B 1/22** (2006.01); **B21B 3/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01); **H01B 5/02** (2006.01); **H01B 13/00** (2006.01)

CPC (source: EP KR US)

B21B 1/22 (2013.01 - KR); **C22C 9/06** (2013.01 - EP KR US); **C22F 1/00** (2013.01 - KR); **C22F 1/08** (2013.01 - EP US); **H01B 1/02** (2013.01 - KR); **B21B 3/00** (2013.01 - EP US)

Citation (search report)

- [X] JP 2004131829 A 20040430 - NIKKO METAL MFG CO LTD
- [XI] JP 2002317231 A 20021031 - NIPPON MINING CO
- [A] US 4656003 A 19870407 - MIYAFUJI MOTOHISA [JP], et al
- [A] JP 2004149873 A 20040527 - NIKKO METAL MFG CO LTD
- See references of WO 2008044680A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

US 2009229716 A1 20090917; EP 2088215 A1 20090812; EP 2088215 A4 20120627; JP 2008115465 A 20080522; JP 5170866 B2 20130327; KR 20090064473 A 20090618; TW 200829707 A 20080716; TW I412611 B 20131021; WO 2008044680 A1 20080417

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US 42112809 A 20090409; EP 07829424 A 20071009; JP 2007069686 W 20071009; JP 2007260386 A 20071003; KR 20097008901 A 20090429; TW 96137423 A 20071005